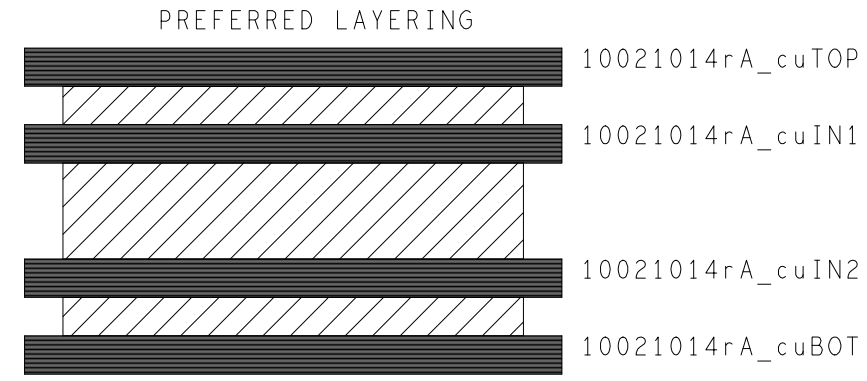


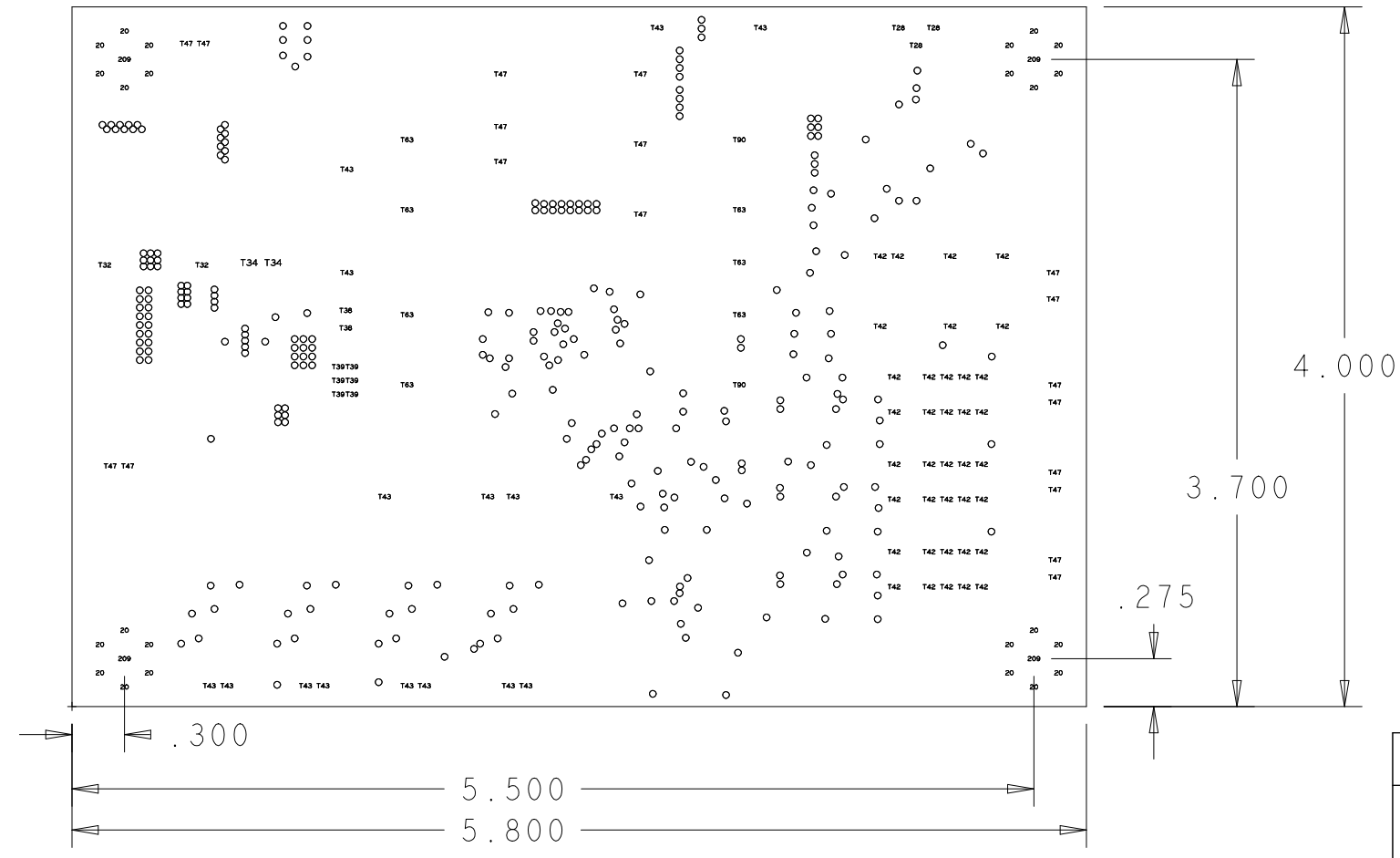
CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
3. MATERIAL:
 - a. FR4 PER IPC 4101B/24, /26, OR /28.
 - b. SIGNAL LAYERS TO BE 2 OZ. COPPER.
 - c. PLANE LAYERS TO BE 1 OZ. COPPER.
 - d. OVERALL THICKNESS TO BE 0.062" +/- 10%
4. LEGEND:
 - a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:
 - a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR GREEN, BOTH SIDES.
6. PLATING FINISH:
 - a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
 - ~~b. IMMERSION SILVER TAG.~~
7. PROCESS ALLOWANCES:
 - a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH
 - b. HOLE DIMENSIONS APPLY AFTER PLATING.
 - c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.
 - d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
 - e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
 - f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
 - g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
o	10.0	PLATED	301
20	20.0	PLATED	24
T28	28.0	PLATED	3
T32	32.0	PLATED	2
T34	34.0	PLATED	2
T38	38.0	PLATED	2
T39	39.0	PLATED	6
T42	42.0	PLATED	37
T43	43.0	PLATED	16
T47	47.0	PLATED	18
T63	63.0	PLATED	7
T90	90.0	PLATED	2
209	209.0	PLATED	4



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +	SIGNATURES	DATE	swFOCE SENSOR NODE		
	DESIGNED BY: CHAD KEYC		SIZE B	REVISION B	DWG NO 10021014
	LAYOUT BY: JOSE ROSAL		SCALE 1-1		SHEET 1-1

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